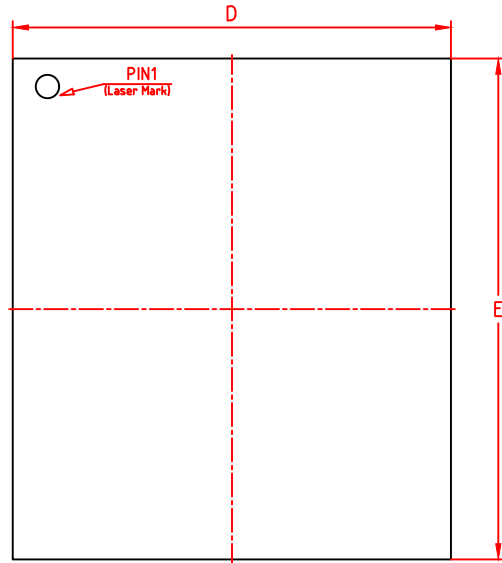


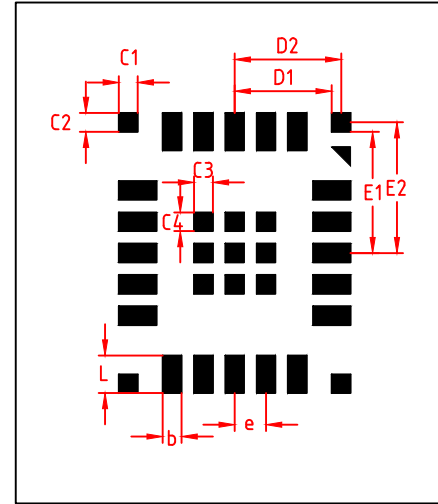
TOP VIEW  
正视图



SIDE VIEW  
侧视图



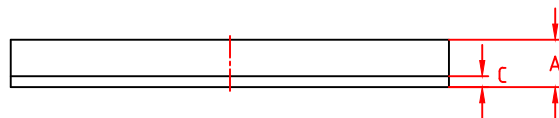
BOTTOM VIEW  
背视图




机械尺寸/mm

字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	0.700	0.750	0.800
C	0.193	0.203	0.213
C1	0.550	0.600	0.650
C2	0.550	0.600	0.650
C3	0.550	0.600	0.650
C4	0.550	0.600	0.650
b	0.550	0.600	0.650
D	9.000	/	14.000
D1	3.050	3.100	3.150
D2	3.350	3.400	3.450
E	11.340	/	16.000
E1	3.825	3.875	3.925
E2	4.125	4.175	4.225
e	1.000 BSC		
L	1.150	1.200	1.250

SIDE VIEW  
侧视图



 <b>池州华宇电子科技股份有限公司</b> CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD					制图: Draw	NINGLIN 2024. 1. 24
图号 Drawing NO.	HY-POD-LGA0012				制图核查: Drawing review	
Title 产品外形图	PACKAGE OUTLINE DIMENSIONS LGA24 (16.0×14.0×0.75-P1.00)				审核: Checker	
幅图 size	页数 page	单位 unit	比例 scale	视图 view	核准: Approved	
A4	1	mm	1:1	☉ □		